IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type *	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfc Information				
upplier Inform	ation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requeste	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Ianufacturing Site	V	Veight*	UOM	Unit Type
	FSB50450S SPM5 V1 IN		SPM5 V1 INV 500V	INV 500V 2.4ohm		2023-06-08 TAB		AB	3214.15		mg	Each		
	Process Information		' 1D	A.11	CED 020 MCI	D. C	D 1 D	D 1 T		M T (P. 1	T	N. I	CD C	,
			,		STD-020 MSL	Rating		Peak Process Body Temperat					er of Reflow Cyc	cles
•	n (Sn) - annealed	C	U Alloy	[3]			245		IC.	30	second	ls 3		
omments														
	3 Rated item requires B		` `											
r more informatio	on regarding material co	mposition p	please refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	20.5	mg	Supplier	Silicon (Si)	7440-21-3		20.5	mg
Die Attach2	1.3	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.039	mg
			Supplier	Miscellaneous	Trade Secret		0.065	mg
			Supplier	Silver (Ag)	7440-22-4		1.105	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.091	mg
Die Attach Solder	4.0	mg	Supplier	Silver (Ag)	7440-22-4		0.08	mg
			A	Lead (Pb)	7439-92-1	7a	3.52	mg
			Supplier	Tin (Sn)	7440-31-5		0.4	mg
Lead Frame	1351.06	mg	Supplier	Silver (Ag)	7440-22-4		19.7001	mg
			В	Nickel (Ni)	7440-02-0		29.6001	mg
			Supplier	Iron (Fe)	7439-89-6		1.35	mg
			Supplier	Copper (Cu)	7440-50-8		1300.0049	mg
			Supplier	Phosphorus (P)	7723-14-0		0.405	mg
Mold Compound-Black	1819.49	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		9.1	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		264.0007	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		18.2	mg
			Supplier	Carbon Black (C)	1333-86-4		8.19	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1519.9993	mg
Plating	13.8	mg	Supplier	Tin (Sn)	7440-31-5		13.8	mg
Wire Bond - Au	4.0	mg	Supplier	Gold (Au)	7440-57-5		4	mg